TOSHIBA CMOS Integrated Circuit Silicon Monolithic

TC78B015BFTG

3-phase Driver for Brushless DC Motors

The TC78B015BFTG is for three-phase full-wave brushless DC motor with 150-degree trapezoid PWM chopper system. They control motor rotational speed by changing the PWM duty, based on the speed control input. Hall signal is supported three sensors for the TC78B015BFTG.

P-WQFN36-0505-0.50-001

Weight: 0.06 g (typ.)

Features

- Three-phase full wave drive
- 150-degree trapezoid PWM chopper system
- Soft switching
- Hall amplifier (hall element / hall IC):

3-sensor drive

- Power supply: absolute maximum voltage: 25 V
- Output current: absolute maximum current: 3 A
- Selectable rotational speed command input signal:

Pulse duty signal input/analog voltage input/PWM signal input

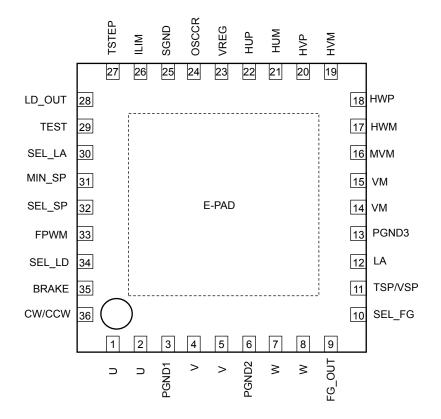
- Selectable PWM frequency
- Adjustable minimum duty in PWM control
- · Adjustable speed ratio in PWM control
- Selectable lead angle control function: Auto lead angle function/External lead angle control (32 steps correspond to 0 to 58°)
- Selectable rotation direction
- Brake function terminal
- Selectable lock detection function
- Restart function
- Rotation frequency signal (FG_OUT):

1 pulse/electrical angle 360°, 3 pulse/ electrical angle 360°

- Lock detection signal (LD_OUT)
- Power supply voltage monitoring function
- Overcurrent detection circuit (ISD)
- Thermal shutdown circuit (TSD)
- Under voltage lockout circuit (UVLO)
- Current limit circuit
- · Adjustable start conditions

Pin assignment

<Top view>



Note 1: Design the pattern in consideration of the heat design because the back side (E-PAD) has the role of heat radiation. The back side (E-PAD) should be connected to GND because it is connected to the back of the chip electrically.

Note 2: There are four pairs of terminals named U, V, W, and VM. Connect two each of the terminals which has the same pin symbol via external patterns. Regarding GND, connect PGND1, PGND2, PGND3, and SGND via external patterns. PGND1 and PGND2 are short-circuited in the IC.

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Pin description

Pin number	Symbol	I/O	Pin description		
1	U	0	Output terminal for U phase		
2	U	0	Output terminal for U phase		
3	PGND1	_	Power ground terminal (source of output Nch MOS transistor)		
4	V	0	Output terminal for V phase		
5	V	0	Output terminal for V phase		
6	PGND2	_	Power ground terminal (source of output Nch MOS transistor)		
7	W	0	Output terminal for W phase		
8	W	0	Output terminal for W phase		
9	FG_OUT	0	Output terminal for rotation frequency		
10	SEL_FG	1	Selectable terminal for FG frequency division ratio		
11	TSP/VSP	I	Input terminal for rotational speed command		
12	LA	1	Input terminal for setting lead angle		
13	PGND3	_	Power ground terminal (GND for pre-driver block)		
14	VM	_	Power supply terminal for motor		
15	VM	_	Power supply terminal for motor		
16	MVM	1	Terminal for monitoring power supply		
17	HWM	Į	W-phase Hall-signal input (-)		
18	HWP	ı	W-phase Hall-signal input (+)		
19	HVM	I	V-phase Hall-signal input (-)		
20	HVP	ı	V-phase Hall-signal input (+)		
21	HUM	I	J-phase Hall-signal input (−)		
22	HUP	ı	U-phase Hall-signal input (+)		
23	VREG	_	Output terminal for reference voltage (5 V)		
24	OSCCR	_	Terminal for setting internal oscillator circuit		
25	SGND	_	Signal ground terminal		
26	ILIM	I	Terminal for setting current limit		
27	TSTEP	_	Terminal for setting acceleration and deceleration time of PWM duty		
28	LD_OUT	0	Output terminal for lock detection		
29	TEST	1	Terminal for test		
30	SEL_LA	ı	Input terminal for selecting a method of lead angle or external input		
31	MIN_SP	I	Input terminal for setting minimum output on duty		
32	SEL_SP	I	Input terminal for selecting a method of rotational speed command		
33	FPWM	I	Input terminal for selecting PWM frequency		
34	SEL_LD	ı	Selectable terminal for motor lock detection function		
35	BRAKE	I	Brake on/off terminal		
36	CW/CCW	I,	Input terminal for selecting rotation direction		

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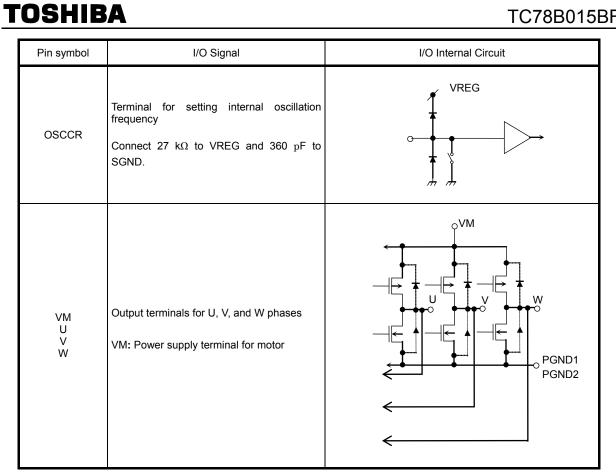
I/O Equivalent circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

Din overhol	I/O Signal	I/O Internal Circuit
Pin symbol	I/O Signal	I/O Internal Circuit
HUP HUM HVP HVM HWP HWM	Input terminal Hysteresis ± 8 mV (typ.)	VREG VREG
CW/CCW BRAKE	Input terminal H: 2 V (min) L: 0.8 V (max)	50 kΩ (typ.)
SEL_SP SEL_LA	Input terminal When leaving the terminal open, it is set to Middle level. When leaving the terminal open, plenty of evaluations using actual systems are required before using.	VREG 50 kΩ (typ.) 50 kΩ (typ.)
SEL_FG MIN_SP LA FPWM SEL_LD	Input terminal Applying a voltage to the terminals is required.	VREG W
TSP/VSP	Input terminal for rotational speed command	

Pin symbol	I/O Signal	I/O Internal Circuit
VREG	Output terminal for reference voltage VREG = 5 V (typ.) Connect a capacitor (Recommended value: 0.1 µF) for voltage stability between SGND.	VM VM VREG
FG_OUT LD_OUT	Open drain output Pull-up the terminals externally to output high level.	
ILIM	Terminal for setting current limit Connect the resistance between SGND	VREG VREG
MVM	Input terminal for monitoring power supply voltage Applying a voltage to the terminals is required.	
TEST	Test terminal	VREG TO THE TOTAL
TSTEP	Terminal for setting time Connect a capacitor to SGND.	VREG

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Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Power supply voltage	VM	25	V
Input voltage	V _{IN1} (Note 1)	−0.3 to 6	V
Input voitage	V _{IN2} (Note 2)	−0.3 to VREG + 0.3	٧
Output voltage	V _{OUT1} (Note 3)	25	V
Output voltage	V _{OUT2} (Note 4)	UT2 (Note 4) 25	
	I _{OUT1} (Note 5)	3 (Note 8)	Α
Output current	I _{OUT2} (Note 6)	10	mA
	I _{OUT3} (Note 7)	40	mA
Power dissipation	P _D	4.1 (Note 9)	W
Operating temperature	T _{opr} -40 to 85		°C
Storage temperature	T _{stg}	−55 to 150	°C

Note: The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings. Exceeding the ratings may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion. Please use within the specified operating ranges.

Note 1: Terminal for V_{IN1}: TSP/VSP, CW/CCW, and BRAKE

Note 2: Terminal for V_{IN2} : HUP, HUM, HVP, HVM, HWP, HWM, SEL_LD, SEL_FG, CW/CCW, BRAKE, ILIM, MIN_SP, MVM, SEL_SP, LA, FPWM, SEL_LA, and TEST

Note 3: Terminal for V_{OUT1}: U, V, and W

Note 4: Terminal for VOUT2: FG_OUT and LD_OUT

Note 5: Terminal for IOUT1: U, V, and W

Note 6: Terminal for IOUT2: FG_OUT and LD_OUT

Note 7: Terminal for IOUT3: VREG

Note 8: Output current may be limited by the ambient temperature or the device implementation. The maximum junction temperature should not exceed Tj (max) = 150°C.

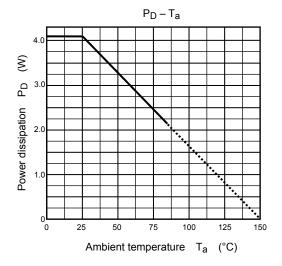
Note 9: When mounted on a board (4 layers, FR4, 76.2 mm × 114.3 mm × 1.6 mm), Rth (j-a) = 30.5°C/W

Operating ranges

Characteristics	Symbol	Operating range	Unit
Power supply voltage	VM _{opr}	6 to 22 V	V

Power dissipation (reference data)

When mounted on a board (4 layers, FR4, 76.2 mm \times 114.3 mm \times 1.6 mm), Rth (j-a) = 30.5 $^{\circ}$ C/W



Electrical Characteristics (Ta = 25°C)

Characteristics		Sym	bol	Test Conditions	Min	Тур.	Max	Unit	
Power supply current		IIV	1	IVreg = 0 mA	_	6.0	8.5	mA	
	IIN1A		1A	TSP/VSP (SEL_SP = VREG)		_	1		
		IIN1E	D(H)	TSP/VSP = 5 V (SEL_SP = Open, GND)	_	100	150		
		IIN1E	D(L)	TSP/VSP = 0 V (SEL_SP = Open, GND)	-1	1	1		
		IIN	2	SEL_FG, MIN_SP, LA, FPWM, SEL_LD	-1	_	1		
Input current		IN3((H)	V _{IN} = 5 V SEL_SP, LA, SEL_LA	_	100	150	μА	
		IN3	(L)	V _{IN} = 0V SEL_SP, LA, SEL_LA	-150	-100	_		
		IN4((H)	V _{IN} = 5 V CW/CCW, BRAKE	_	100	150		
		IN4	(L)	V _{IN} = 0 V CW/CCW, BRAKE	-1	0	_		
		IN	5	MVM	-1	_	1		
	Input sensitivity	Vs	3	Differential input	40	_	_	mVpp	
Hall element input	In-phase voltage range	V _V	٧	_	0.5	_	3.5	V	
	Input hysteresis	VI	1	(Reference data)	±4	±8	±12	mV	
Hall IC input		V _{IN4}	Н	HUP, HVP, HWP HUM, HVM, HWM = VREG/2	V _{REG}	_	V _{REG}	V	
			L	110.11, 111.11, 111.11	0	_	0.8		
		V _{IN1} (H)		TSP/VSP	2.0	_	5.5	-	
		V _{IN1} (L)		(SEL_SP = Open, GND)	GND	_	0.8	- -	
		V _{IN2} (H)		CW/CCW, BRAKE	2.0	_	5.5		
		V _{IN2}	(L)	CW/CCW, BRAKE	GND	_	0.8		
Input voltage		V _{IN3} (H)		MVM L→H: 150-degree commutation →120-degree commutation	1.9	2.0	2.1	V	
				MVM H→L: 120-degree commutation→150-degree commutation	1.7	1.8	1.9		
		V1h	iys	(Reference data) TSP/VSP SEL_SP = GND	0.3	0.4	0.5	V	
Input hysteresis range		V2hys		(Reference data) CW/CCW, BRAKE	0.3	0.4	0.5	V	
Output low voltage of FG_OUT/LD_OUT		Vol	JT	I _{OUT} = 5 mA	GND	_	0.5	V	
Leakage current of FG_OUT/LD_OUT		I _{LO}	JT	(Reference data) V _{OUT} = 22V	_	0	2	μΑ	
Output on resistance of U, V, W		R _{ON} (H+L)	I _{OUT} = 1 A	_	0.24	0.33	Ω	
Output leakage current of U, V, W		IL (H)		V _{OUT} = 0 V	-10	0	_	μА	
Jusput loundage of		I _L (L)	(Reference data) V _{OUT} = 22V	_	0	10	μι	
Masking time for limit	detecting current	TR	S	(Reference data)	_	1.2	_	μS	
Detection error of	current limit	ΔΙΟ	UT	lout (U/V/W) = 1 A, ILIM: 39 kΩ	-10	_	10	%	

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Characteristics	Symbol	Test Conditions	Min	Тур.	Max	Unit
Relative detection error of current limit	ΔIOUT_R	(Reference data) lout (U/V/W) = 1 A, ILIM: $39 \text{ k}\Omega$ Measured value of each upper-and-lower phase for average value of upper-and-lower phase	-8.5	_	8.5	%
	FPWM3	(Reference data)FPWM = "3"	22.5	25	27.5	
DWM assillation fraguency	FPWM2	(Reference data)FPWM = "2"	180	200	220	kHz
PWM oscillation frequency	FPWM1	(Reference data)FPWM = "1"	90	100	110	KHZ
	FPWM0	(Reference data)FPWM = "0"	45	50	55	
OSC frequency	osc	(Reference data)OSCCR: 27 kΩ,360 pF	11.7	13	14.3	MHz
Setting time of TSTEP terminal	Tsoft	(Reference data)TSTEP = 0.01 μF	_	0.100	_	S
Lock detection time	Tlock1	(Reference data)SEL_LD = "0"	_	0.5	_	S
Restart time after lock	Tlock2	(Reference data)SEL_LD = "0"	_	5	_	S
Masking time for detecting overcurrent	TISD	(Reference data)	_	1.9	_	μS
Current when overcurrent detection operates	ISD	(Reference data)	3	4.5	6	Α
Thermal shutdown circuit	TSD	(Reference data)	150	165	180	°C
Thermal shuldown circuit	TSDhys	(Reference data) Hysteresis for restart	_	15	_	C
Under lockout voltage of VM terminal	VMUVLO	_	5.0	5.3	5.6	V
Under lockout restarting voltage of VM terminal	VMUVLOR	_	5.3	5.6	5.9	V
VREG output voltage	VREG	IVREG = -40 mA (Note 1)	4.7	5	5.3	V

(Reference data): No shipping inspection

Note 1: There is a possibility that VREG output voltage does not reach the minimum value in the above Electrical Characteristics when the power supply voltage is less than the operating ranges. Moreover, it depends on VM and the conditions of IVREG. Therefore, confirm there are not any problems by evaluating actual systems at about VMUVLO.

The relation of setting steps and terminal voltage

SEL_SP	SEL_FG	FPWM	MIN_SP	LA (Auto lead	LA (External	Input vo (Written b	Itage (V) by VREG)	Input vol (When VR	
SEL_LA	SEL_FG	SEL_LD		angle: SEL_LA = "1")	input: SEL_LA = "0")	Min	Max	Min	Max
			_		31	Vreg/256*160	Vreg	3.125	5
2		3	8	_	30	Vreg/256*155	Vreg/256*159	3.027	3.105
				7	29	Vreg/256*150	Vreg/256*154	2.93	3.008
] _		28	Vreg/256*145	Vreg/256*149	2.832	2.910
			7		27	Vreg/256*140	Vreg/256*144	2.734	2.813
					26	Vreg/256*135	Vreg/256*139	2.637	2.715
	1			6	25	Vreg/256*130	Vreg/256*134	2.539	2.617
		2	6		24	Vreg/256*125	Vreg/256*129	2.441	2.520
		2			23	Vreg/256*120	Vreg/256*124	2.344	2.422
				5	22	Vreg/256*115	Vreg/256*119	2.246	2.324
				3	21	Vreg/256*110	Vreg/256*114	2.148	2.227
			5		20	Vreg/256*105	Vreg/256*109	2.051	2.129
1			4	4	19	Vreg/256*100	Vreg/256*104	1.953	2.031
'					18	Vreg/256*95	Vreg/256*99	1.855	1.934
					17	Vreg/256*90	Vreg/256*94	1.758	1.836
					16	Vreg/256*85	Vreg/256*89	1.66	1.738
				3	15	Vreg/256*80	Vreg/256*84	1.563	1.641
		1			14	Vreg/256*75	Vreg/256*79	1.465	1.543
		'			13	Vreg/256*70	Vreg/256*74	1.367	1.445
					12	Vreg/256*65	Vreg/256*69	1.27	1.348
					11	Vreg/256*60	Vreg/256*64	1.172	1.250
	0			2	10	Vreg/256*55	Vreg/256*59	1.074	1.152
	O				9	Vreg/256*50	Vreg/256*54	0.977	1.055
			2		8	Vreg/256*45	Vreg/256*49	0.879	0.957
			_		7	Vreg/256*40	Vreg/256*44	0.781	0.859
					6	Vreg/256*35	Vreg/256*39	0.684	0.762
				1	5	Vreg/256*30	Vreg/256*34	0.586	0.664
0		0			4	Vreg/256*25	Vreg/256*29	0.488	0.566
			1		3	Vreg/256*20	Vreg/256*24	0.391	0.469
				0	2	Vreg/256*15	Vreg/256*19	0.293	0.371
			0		1	Vreg/256*10	Vreg/256*14	0.195	0.273
					0	0	Vreg/256*9	0	0.176

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Functional Description

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes. Timing charts may be simplified for explanatory purposes.

1. Basic operation

During startup, the motor is driven by 120-degree commutation. After the position signal frequency reaches the rotational speed of 1 Hz, the motor is driven by 150-degree PWM drive by estimating the rotor positions from the position signals.

Startup to 1 Hz: 120-degree PWM drive More than 1Hz: 150-degree PWM drive

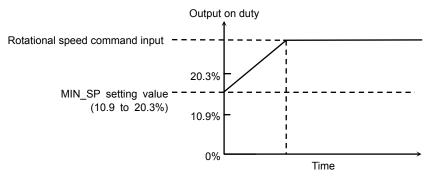
2. Startup operation

On duty at startup is determined by setting MIN_SP terminal.

1) When MIN_SP = "1 to 7" (10.9% to 20.3%)

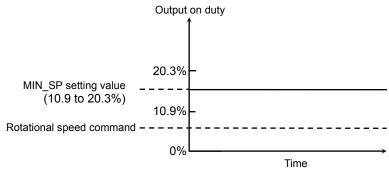
•If rotational speed command > MIN_SP

The output starts from the level corresponding to the on duty configured by MIN_SP terminal.



•If rotational speed command \leq MIN SP

The output starts from the level corresponding to the on duty configured by MIN_SP terminal.

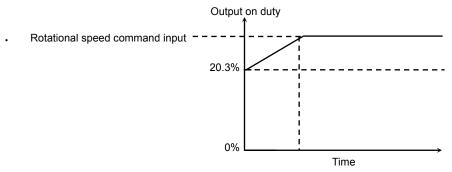


2) When MIN_SP = "8"

•If Rotational speed command > 20.3%

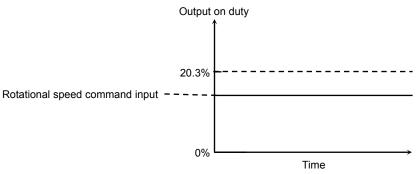
The output starts from the level corresponding to the on duty of 20.3%.

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•If Rotational speed command ≤ 20.3%

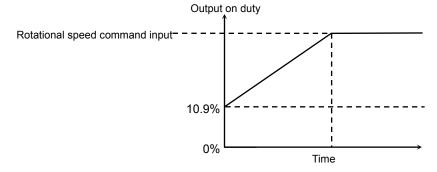
The output starts from the level corresponding to the on duty of the rotational speed command input.



3) When $MIN_SP = "0"$

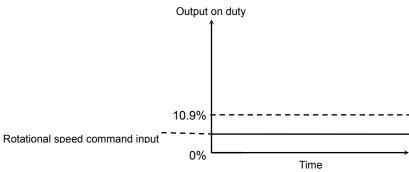
•If Rotational speed command > 10.9%

The output starts from the level corresponding to the on duty of 10.9%.



•If Rotational speed command ≤ 10.9%

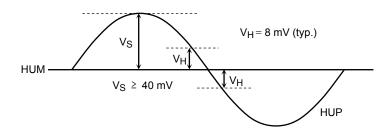
The output starts from the level corresponding to the on duty of the rotational speed command input.



3. Position detection terminal

<Hall element input>

In-phase voltage range: $V_W = 0.5$ to 3.5 V Input hysteresis: $V_H = 8$ mV (typ.)



<Hall IC input>

Conditions: HUP, HVP, HWP = GND to VREG HUM, HVM, HWM = VREG/2

4. Operation in abnormality detection

The following states are detected as abnormalities:

- 1. The ISD circuit is activated.
- 2. The TSD circuit is activated.
- 3. The motor lockout detection is activated.
- 4. Overvoltage detection is activated.

If either of the above abnormality of 1, 2, or 3 is detected, the LD_OUT terminal outputs low level until 150-degree PWM drive starts.

5. Motor lockout detection

If the position signal does not change within the term of Ton after inputting a start command, the operation turns off, and the drive in the term of Ton and the non-drive in the term of Toff set by SEL_LD terminal are repeated alternatively.

When on duty = 0% as a rotational speed command is input into TSP/VSP terminal, the term of Toff is released. After a start command signal is input into TSP/VSP terminal, the drive will restart.

To release the abnormality detection, input a rotational speed command of 'on duty = 0%' for 2ms period or more.

Ton and Toff are set by SEL_LD terminal as follows.

Number of steps set by SEL_LD terminal	Functional description
3	Motor lockout detection does not work.
2	Ton = 1s(typ.), Toff = 10s(typ.)
1	Ton = 0.5s(typ.), Toff = 10s(typ.)
0	Ton = 0.5s(typ.), Toff = 5s(typ.)

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6. Forward /Reverse rotation direction switching

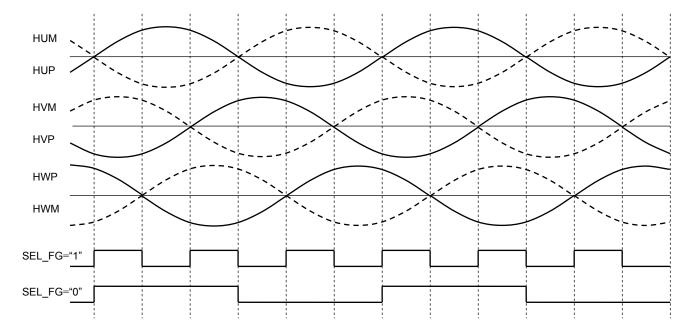
CW/CCW = Low: Forward direction, CW/CCW = High: Reverse direction.

CW/CCW	Order of conduction phase of output			
L	Forward rotation direction: $U \rightarrow V \rightarrow W \rightarrow U \rightarrow \cdot \cdot \cdot$			
Н	Reverse rotation direction: W→V→U→W→・・・			

7. Rotational speed output

A rotation pulse based upon hall signals is output. Either 1 pulse or 3 pulses per electrical angle can be selected by SEL_FG terminal.

Number of steps set by SEL_FG terminal	FG_OUT
1	3 pulses/ electrical angle
0	1 pulse/ electrical angle



8. Rotational speed command

Startup, stop and motor rotational speed which is set by output PWM duty are able to be controlled by an input signal into TSP/VSP terminal.

Pulse duty control, analog voltage control, or direct PWM control can be selected as a mode of TSP/VSP terminal by the number of steps set by SEL_SP terminal.

Number of steps set by SEL_SP terminal	Input control at TSP/VSP terminal
2	Analog voltage control
1	Pulse duty control
0	Direct PWM control

1) Relation of TSP/VSP terminal voltage and output PWM duty in controlling analog voltage (SEL_SP="2")

When the voltage of TSP/VSP terminal ≥ 0.625 V, startup sequence starts. When the voltage of TSP/VSP terminal < 0.625 V, the sequence is reset.

 $0 \le VSP/TSP$ (when analog voltage control) $\le VAD$ (L): 0.625 V (typ.)

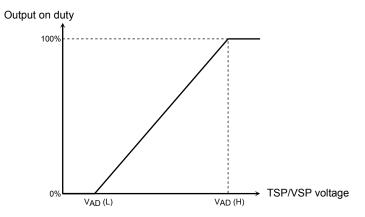
 \rightarrow Duty = 0%

 V_{AD} (L): 0.625 V (typ.) \leq VSP/TSP (when analog voltage control) \leq V_{AD} (H): 3.125 V (typ.)

 \rightarrow See the below figure. (1/128 to 128/128)

 V_{AD} (H) 3.125 V (typ.) \leq VSP/TSP (when analog voltage control) \leq VREG

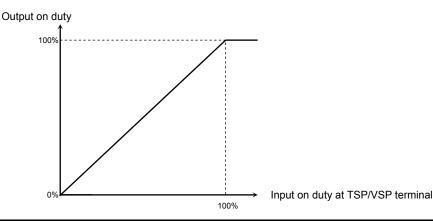
 \rightarrow Duty = 100% (128/128)



2) Relation of TSP/VSP terminal voltage and output PWM duty in controlling pulse duty (SEL_SP="1")

When a PWM signal is input into TSP/VSP terminal, startup sequence starts.

The pulse frequency input into TSP/VSP terminal should be set from 1 kHz to 100 kHz. Because input signal may be ineffective when on duty is for $0.2~\mu s$ or less. Because the operation may be judged off state when output off duty is for 1 ms or more.



3) Relation of TSP/VSP terminal voltage and output PWM duty in controlling direct PWM (SEL_SP = "0")

When a PWM signal is input into TSP/VSP terminal, startup sequence starts.

The pulse frequency of input into TSP/VSP terminal should be set from 23 kHz to 100 kHz.

The PWM frequency of 150-degree PWM drive is determined by the input signal of TSP/VSP terminal.

When SEL_SP is "0", configurations of TSTEP terminal and MIN_SP terminal become invalid, and the functions of control configuration of acceleration and deceleration and configuration of minimum output on-duty become invalid.

9. Setting minimum output on duty

Minimum output on duty is determined by the input voltage into MIN_SP terminal. In setting SEL_SP = "0", the minimum output on-duty for MIN_SP terminal becomes invalid.

Number of steps set by MIN_SP terminal	Minimum output duty	Duty during startup
8	0%	Rotational speed command value > 20.3%: 20.3% Rotational speed command value ≤ 20.3%: Rotational speed command value
7	20.3%	20.3%
6	18.8%	18.8%
5	17.2%	17.2%
4	15.6%	15.6%
3	14.1%	14.1%
2	12.5%	12.5%
1	10.9%	10.9%
0	0%	Rotational speed command value > 10.9%: 10.9% Rotational speed command value ≤ 10.9%: Rotational speed command value

10. PWM frequency

Output PWM frequency either in analog voltage control or in pulse duty control is determined by input voltage at FPWM terminal.

Output PWM frequency should be much higher than the electrical frequency of the motor. Please determine the value within switching performance of the drive circuits.

Number of steps set by FPWM terminal	PWM frequency
3	25 kHz
2	200 kHz
1	100 kHz
0	50 kHz

11. Lead angle control

Lead angle control mode is determined by setting both SEL_LA and LA terminal.

Number of steps set by SEL_LA terminal	Functional description			
2	Test mode			
1	Auto lead angle: Auto lead angle mode is selected by input voltage of LA terminal			
0	External input: Lead angle value is configured by input voltage of LA terminal			

1)Auto lead angle (SEL_LA = "1")

The threshold of the frequency has hysteresis +0 Hz/-50 Hz.

Lead angle value [deg]

Edda di	Lead angle value [deg]									
Number			Electrical frequency [Hz]							
of steps set by LA terminal	0 to 100	100 to 200	200 to 300	300 to 400	400 to 500	500 to 600	600 to 700	700 to 800	800 to 900	900 to 1000
7	0	1.875	1.875	1.875	1.875	3.750	3.750	3.750	3.750	5.625
6	0	1.875	1.875	3.750	3.750	5.625	5.625	7.500	7.500	9.325
5	0	1.875	1.875	3.750	5.625	7.500	7.500	9.325	11.250	13.125
4	0	1.875	3.750	5.625	9.325	11.250	13.125	15.000	18.750	20.625
3	0	1.875	5.625	7.500	11.250	13.125	16.875	18.750	22.500	24.375
2	0	3.750	5.625	9.325	13.125	16.875	18.750	22.500	26.250	30.000
1	0	3.750	7.500	11.250	15.000	18.750	22.500	26.250	30.000	33.750
0	0	1.875	3.750	5.625	7.500	9.325	11.250	13.125	15.000	16.875

Lead angle value $[\deg]$

Number					Electrica	al freque	ncy [Hz]				
of steps set by LA terminal	1000 to 1100	1100 to 1200	1200 to 1300	1300 to 1400	1400 to 1500	1500 to 1600	1600 to 1700	1700 to 1800	1800 to 1900	1900 to 2000	More than 2000
7	5.625	5.625	5.625	7.500	7.500	7.500	7.500	9.375	9.375	9.375	9.375
6	9.325	11.250	11.250	13.125	13.125	15.000	15.000	16.875	16.875	18.750	18.750
5	13.125	15.000	16.875	18.750	18.750	20.625	22.500	24.375	24.375	26.250	28.125
4	22.500	24.375	28.125	30.000	31.875	33.750	37.500	39.375	41.250	43.125	46.875
3	28.125	30.000	33.750	35.625	39.375	41.250	45.000	46.875	50.625	52.500	56.250
2	31.875	35.625	39.375	43.125	45.000	48.750	52.500	56.250	58.125	58.125	58.125
1	37.500	41.250	45.000	48.750	52.500	56.250	56.250	56.250	56.250	56.250	56.250
0	18.750	20.625	22.500	24.375	26.250	28.125	30.000	31.875	33.750	35.625	37.500



2) External input (SEL_LA = "0")

Lead angle in the range of 0° to 58.125° as commutation signals which correspond to the induced voltage can be adjusted.

The range from 0 V to $3.125~\mathrm{V}$ as analog input voltage into LA terminal is divided into $32~\mathrm{parts}$.

Input voltage into LA terminal = 0 V: lead angle = 0° .

Input voltage into LA terminal = 3.125 V: lead angle = 58.125°.

Input voltage ≥ 3.125 V, input voltage: lead angle = 58.125°.

(Design value)

Number of steps	LA [V]	Lead angle [deg]	Number of steps	LA [V]	Lead angle [deg]
31	3.125	58.125	15	1.563	28.125
30	3.027	56.250	14	1.465	26.250
29	2.930	54.375	13	1.367	24.375
28	2.832	52.500	12	1.270	22.500
27	2.734	50.625	11	1.172	20.625
26	2.637	48.750	10	1.074	18.750
25	2.539	46.875	9	0.977	16.875
24	2.441	45.000	8	0.879	15.000
23	2.344	43.125	7	0.781	13.125
22	2.246	41.250	6	0.684	11.250
21	2.148	39.375	5	0.586	9.375
20	2.051	37.500	4	0.488	7.500
19	1.953	35.625	3	0.391	5.625
18	1.855	33.750	2	0.293	3.750
17	1.758	31.875	1	0.195	1.875
16	1.660	30.000	0	0.000	0.000

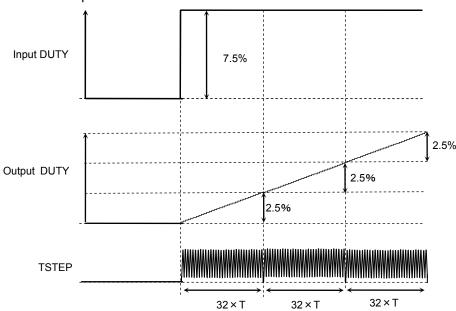
12. Acceleration and deceleration control setting

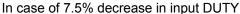
Time to reflect the duty of the input control signal of TSP/VSP terminal in the output duty during acceleration and deceleration can be set by connecting the capacitor to TSTEP terminal. (About 0.078%/T) Therefore, the rotation speed can accelerate and slow down gradually in startup. However, when change of the duty of an input control signal is 2.5% or less, it is reflected in output duty for every PWM cycle. Acceleration and deceleration time: (For example) When $C=0.01~\mu F,~32\times T=32\times 0.313\times C\times 10^6=$ about 0.100 s.

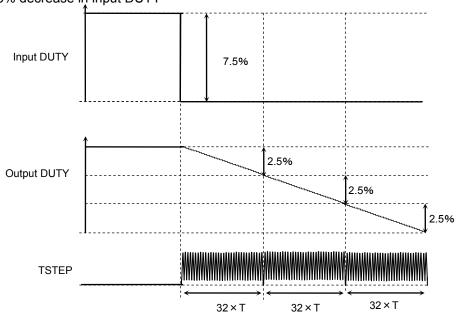
When the speed command that the output on duty is 0% is inputted during operation, the deceleration function becomes invalid, and the output is turned off.

At this time, an output duty is reset to 0%. When restarting, please input a start command signal to TSP/VSP pin after inputting a speed control command that the output on duty is 0% for 2 ms or more.

In case of 7.5% increase in input DUTY







13. Brake function

If high level is input into BRAKE terminal, the reverse brake works to stop the motor operation.

After the input signal into BRAKE terminal is changed from L level to H level during the motor rotation, the reverse brake works until the position signal frequency becomes 40 Hz. When the position signal frequency is less than 40 Hz, the motor will stop.

However, when the input signal into BRAKE terminal is changed from L level to H level under the condition that the output duty command of TSP/VSP terminal is 0%, the operation sequence is shown as the below table.

BRAKE	Functional description
High	Brake
Low or open	Normal operation

In case the input signal into BRAKE terminal is changed from L level to H level under the condition that the output duty command of TSP/VSP terminal is 0%

Status	Brake sequence
Position signal frequency ≤ 40Hz	Short brake
Position signal frequency > 40Hz	Reverse brake → Short brake

14. Overvoltage monitoring function

When MVM = 2.0 V (typ.) or more, drive mode is 120-degree conduction. MVM has 0.2 V (typ.) of hysteresis. If MVM < 1.8 V (typ.), drive restarts.

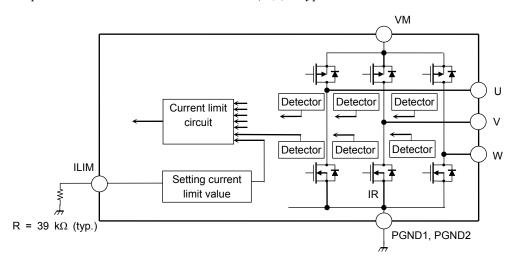
MVM	Function description
MVM ≥ 2.0 V (typ.)	120-degree commutation
MVM < 1.8 V (typ.)	150-degree commutation

15. Current limit circuit

Current limit circuit turns off upper side of the output transistors and limits the current. Driver restarts just when PWM turns on.

Value of current limit is configured by the external resistance.

(Example) When 39 k Ω is set as the resistor (R), I_{OUT} (typ.) = 39000/R = 39000/39000 \simeq 1.0 A





16. Overcurrent detection circuit (ISD)

Six overcurrent detectors are built in each output transistor. If detected value exceeds the absolute maximum rating, all of outputs are turned off (high impedance: Hi-Z).

If output on duty of rotational speed command is set 0%, abnormality detection is released.

Please input a rotational speed command (0% for 2 ms or more) to release the abnormality detection.

17. Thermal shutdown circuit (TSD)

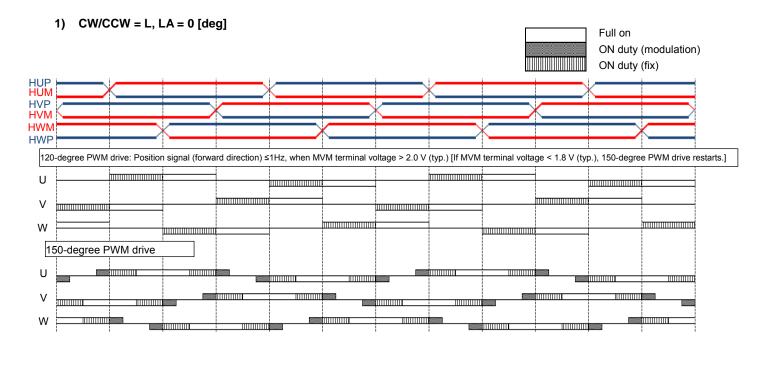
It turns off output (high impedance: Hi-Z), when the junction temperature (Tj) exceeds 165° C (typ.). There is 15° C (typ.) of hysteresis.

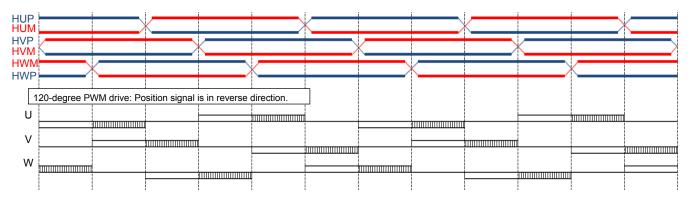
Temperature for restart is $T_{\rm SD}-T_{\rm SDhys}$ after thermal shutdown circuit operates. $T_{\rm SD}=165^{\circ}{\rm C}$ (typ.), $T_{\rm SDhys}=15^{\circ}{\rm C}$ (typ.)

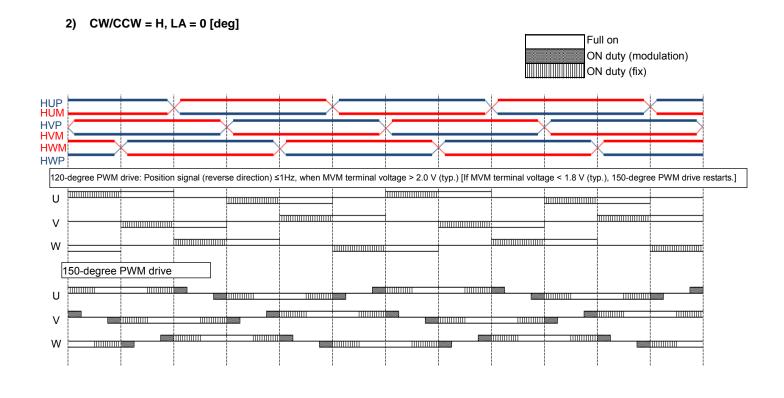
18. Under voltage lockout (UVLO)

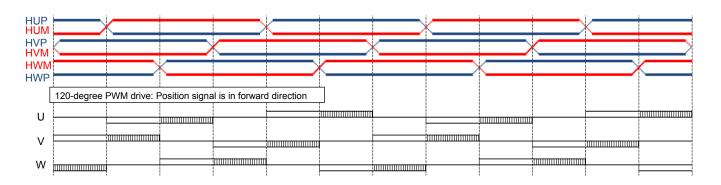
It turns off each output of U, V, W, FG_OUT and LD_OUT (high impedance: Hi-Z), when VM is 5.3 V (typ.) or less. There is 0.3V (typ.) of hysteresis. Voltage for restart is 5.6 V (typ.).

Timing chart



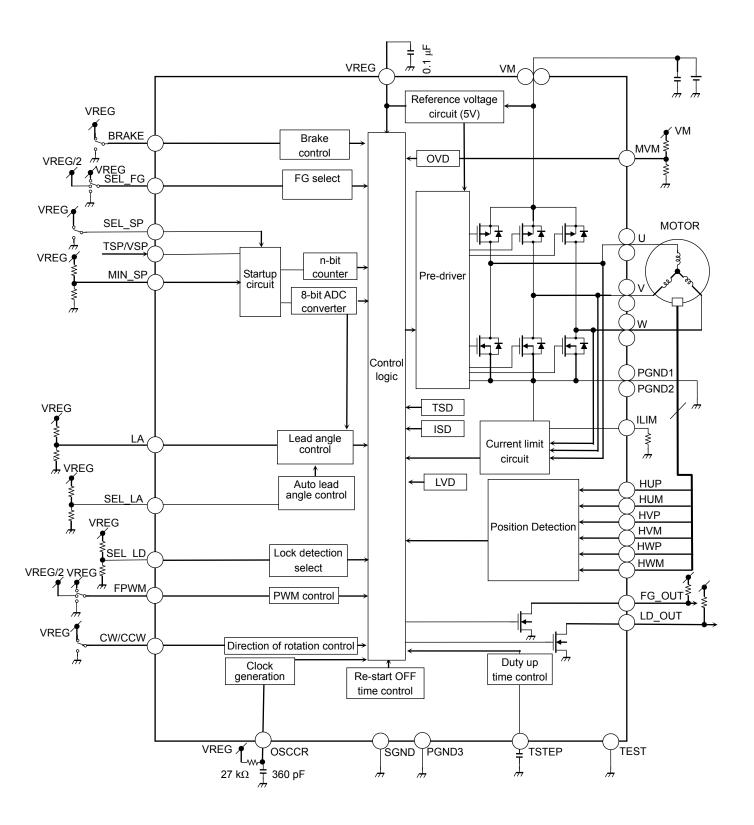






Application circuit example

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes. The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.



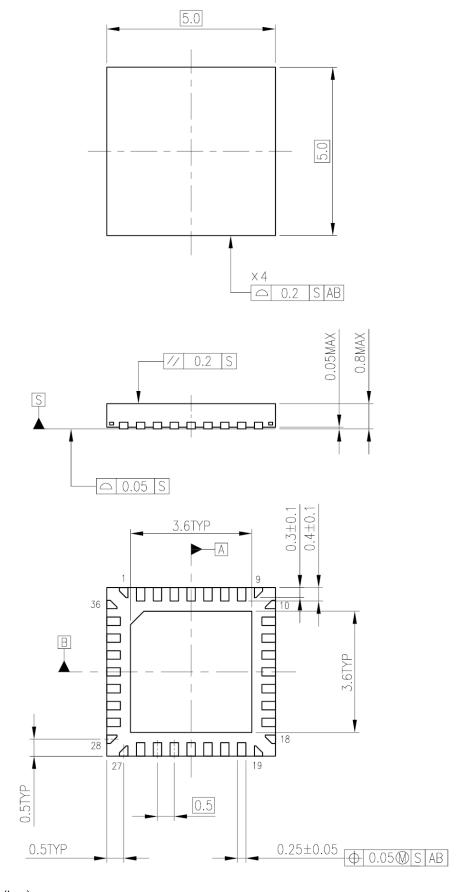
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Package Dimensions

P-WQFN36-0505-0.50-001

 $Unit: \, mm$



Weight: 0.06 g (typ.)

Notes on Contents

1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

3. Timing Charts

Timing charts may be simplified for explanatory purposes.

4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage. Toshiba does not grant any license to any industrial property rights by providing these examples of application circuits.

5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on handling of ICs

- (1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
 Exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition. Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices in the wrong orientation or incorrectly. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause the device breakdown, damage or deterioration, and may result injury by explosion or combustion. In addition, do not use any device that is applied the current with inserting in the wrong orientation or incorrectly even just one time.

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Points to remember on handling of ICs

(1) Over current Protection Circuit

Over current protection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the Over current protection circuits operate against the over current, clear the over current status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current protection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.

(2) Thermal Shutdown Circuit

Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the thermal shutdown circuits operate against the over temperature, clear the heat generation status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the thermal shutdown circuit to not operate properly or IC breakdown before operation.

(3) Heat Radiation Design

In using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (Tj) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

(4) Back-EMF

When a motor rotates in the reverse direction, stops or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond absolute maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.

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